



#### SURFACE MOUNT SCHOTTKY BARRIER DIODE

#### **Features**

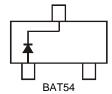
- Low Turn-on Voltage
- Fast Switching
- PN Junction Guard Ring for Transient and ESD Protection
- Lead Free/RoHS Compliant (Note 3)
- "Green" Molding Compound (No Br, Sb) (Note 4)
- Qualified to AEC-Q101 Standards for High Reliability

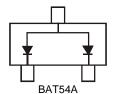
### **Mechanical Data**

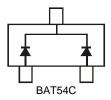
- Case: SOT-23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagrams Below
- Marking Information: See Page 3
- Ordering Information: See Page 2
- Weight: 0.008 grams (approximate)

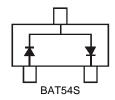


Top View









### **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>R</sub> wm V <sub>R</sub>	30	V	
Forward Continuous Current (Note 2)	l <sub>F</sub>	200	mA	
Repetitive Peak Forward Current		I <sub>FRM</sub>	300	mA
Forward Surge Current	@ t < 1.0s	I <sub>FSM</sub>	600	mA

#### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	P <sub>D</sub>	200	mW
Thermal Resistance, Junction to Ambient Air (Note 2)	$R_{ heta JA}$	500	°C/W
Operating and Storage Temperature Range (Note 5)	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

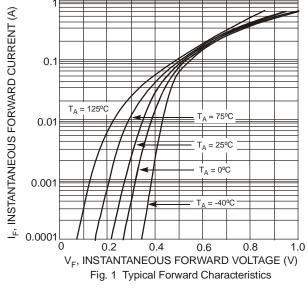
## Electrical Characteristics @TA = 25°C unless otherwise specified

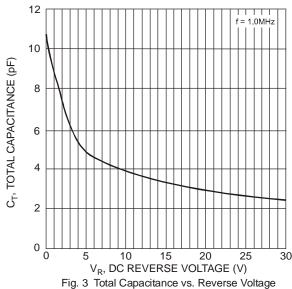
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	$V_{(BR)R}$	30			<b>V</b>	$I_{RS} = 100 \mu A$
Forward Voltage	V <sub>F</sub>	_		240 320 400 500 800	mV	I <sub>F</sub> = 0.1mA I <sub>F</sub> = 1mA I <sub>F</sub> = 10mA I <sub>F</sub> = 30mA I <sub>F</sub> = 100mA
Reverse Leakage Current (Note 1)	I <sub>R</sub>	_		2.0	μΑ	V <sub>R</sub> = 25V
Total Capacitance	C <sub>T</sub>	_		10	рF	$V_R = 1.0V, f = 1.0MHz$
Reverse Recovery Time	t <sub>rr</sub>	_		5.0		$I_F$ = 10mA through $I_R$ = 10mA to $I_R$ = 1.0mA, $R_L$ = 100 $\Omega$

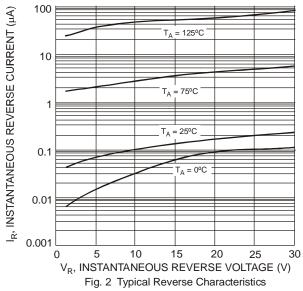
Notes:

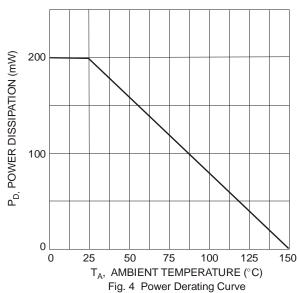
- 1. Short duration test pulse used to minimize self-heating effect.
- 2. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 3. No purposefully added lead.
- Products manufactured with date code VD (Week 50, 2008) and newer are built with Green Molding Compound. Products manufactured with date code
  prior to VD are built with Non-Green Molding Compound and may contain Halogens or Sb<sub>2</sub>O<sub>3</sub> Fire Retardants.
- 5. The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta,JA}$











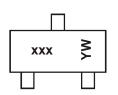
### **Ordering Information** (Note 6)

Part Number	Case	Packaging
BAT54-7-F	SOT-23	3000/Tape & Reel
BAT54A-7-F	SOT-23	3000/Tape & Reel
BAT54C-7-F	SOT-23	3000/Tape & Reel
BAT54S-7-F	SOT-23	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.



## **Marking Information**



xxx = Product Type Marking Code

KL1 = BAT54

KL2 = BAT54A KL3 = BAT54C

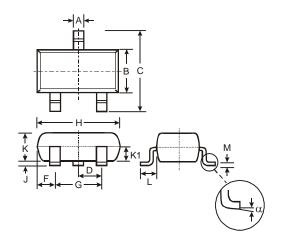
KL4 = BAT54S

YM = Date Code Marking Y = Year (ex: T = 2006) M = Month (ex: 9 = September)

Date Code Key

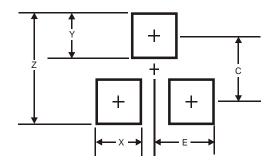
Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	J	K	L	М	N	Р	R	S	Т	U	V	W	Χ	Υ	Z	Α	В	С
Month	Jan	1	Feb	Maı	·	Apr	May	у	Jun	Jul		Aug	Sep	)	Oct	Nov	,	Dec
Code	1		2	3		4	5		6	7		8	9		0	N		D

# **Package Outline Dimensions**



SOT-23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
C	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
7	0.013	0.10	0.05				
K	0.903	1.10	1.00				
K1	-	-	0.400				
L	0.45	0.61	0.55				
М	0.085	0.18	0.11				
α	0°	8°	-				
All	All Dimensions in mm						

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	2.9
X	0.8
Υ	0.9
С	2.0
E	1.35



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